- Ideal for 916.5 MHz Transmitters
- Very Low Series Resistance
- Quartz Stability
- Surface-Mount Ceramic Case with 21 mm² Footprint
- Complies with Directive 2002/95/EC (RoHS)

The RO3144A is a true one-port, surface-acoustic-wave (SAW) resonator in a surface-mount ceramic case. It provides reliable, fundamental-mode, quartz frequency stabilization of fixed-frequency transmitters operating at 916.5 MHz .

### 916.5 MHz SAW

 Resonator
## Absolute Maximum Ratings

| Rating | Value | Units |
| :--- | :---: | :---: |
| CW RF Power Dissipation | 0 | dBm |
| DC Voltage Between Terminals | $\pm 30$ | VDC |
| Case Temperature | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |
| Soldering Temperature, 10 seconds $/ 5$ cycles maximum | 260 | ${ }^{\circ} \mathrm{C}$ |



SM5035-4

## Electrical Characteristics

| Characteristic | Sym | Notes | Minimum | Typical | Maximum | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Frequency, $+25^{\circ} \mathrm{C}$ RO3144A <br>  RO3144A <br>  RO3144A <br>  RO3144A | $\mathrm{f}_{\mathrm{C}}$ | 2,3,4,5 | 916.300 |  | 916.700 | MHz |
|  |  |  | 916.350 |  | 916.650 |  |
|  |  |  | 916.400 |  | 916.600 |  |
| Tolerance from 916.5 MHz RO3144A | ${ }^{\Delta} \mathrm{f}_{\mathrm{C}}$ |  |  |  | $\pm 200$ | kHz |
|  |  |  |  |  | $\pm 150$ |  |
|  |  |  |  |  | $\pm 100$ |  |
| Insertion Loss | IL | 2,5,6 |  | 1.2 | 2.5 | dB |
| Unloaded Q $50 \Omega$ Loaded Q | $Q_{U}$ | 5,6,7 |  | 26500 |  |  |
| $50 \Omega$ Loaded Q | $Q_{L}$ |  |  | 3000 |  |  |
| Turnover Temperature <br> Turnover Frequency <br> Frequency Temperature Coefficient | $\mathrm{T}_{\mathrm{O}}$ | 6,7,8 | 10 | 25 | 40 | ${ }^{\circ} \mathrm{C}$ |
|  | $\mathrm{f}_{0}$ |  |  | ${ }^{\text {f }}$ |  | kHz |
|  | FTC |  |  | 0.032 |  | ppm/ ${ }^{\circ} \mathrm{C}^{2}$ |
| Frequency Aging Absolute Value during the First Year | $\|f \mathrm{~A}\|$ | 1 |  | < $\pm 10$ |  | ppm/yr |
| DC Insulation Resistance between Any Two Terminals |  | 5 | 1.0 |  |  | $\mathrm{M} \Omega$ |
| Motional Resistance <br> Motional Inductance <br> Motional Capacitance <br> Shunt Static Capacitance | $\mathrm{R}_{\mathrm{M}}$ | 5, 6, 7, 9 |  | 13.1 |  | $\Omega$ |
|  | $\mathrm{L}_{M}$ |  |  | 60.3 |  | $\mu \mathrm{H}$ |
|  | $\mathrm{C}_{\mathrm{M}}$ |  |  | . 50 |  | fF |
|  | $\mathrm{C}_{0}$ | 5, 6, 9 |  | 2.09 |  | pF |
| Test Fixture Shunt Inductance | $\mathrm{L}_{\text {TEST }}$ | 2, 7 |  | 14.5 |  | nH |
| Lid Symbolization | RO3144A: 663, RO3144A-1: 897, RO3144A-2: 813, // YWWS |  |  |  |  |  |

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

## Notes:

1. Frequency aging is the change in $f_{C}$ with time and is specified at $+65^{\circ} \mathrm{C}$ or less. Aging may exceed the specification for prolonged temperatures above $+65^{\circ} \mathrm{C}$. Typically, aging is greatest the first year after manufacture, decreasing in subsequent years.
2. The center frequency, $f_{\mathrm{C}}$, is measured at the minimum insertion loss point, $\mathrm{IL}_{\mathrm{MIN}}$, with the resonator in the $50 \Omega$ test system (VSWR $\leq 1.2: 1$ ). The shunt inductance, $\mathrm{L}_{\text {TEST }}$, is tuned for parallel resonance with $\mathrm{C}_{\mathrm{O}}$ at $\mathrm{f}_{\mathrm{C}}$. Typically, $\mathrm{f}_{\text {OSCILLATOR }}$ or $\mathrm{f}_{\text {TRANSMITTER }}$ is approximately equal to the resonator $\mathrm{f}_{\mathrm{C}}$.
3. One or more of the following United States patents apply: 4,454,488 and 4,616,197.
4. Typically, equipment utilizing this device requires emissions testing and government approval, which is the responsibility of the equipment manufacturer.
5. Unless noted otherwise, case temperature $\mathrm{T}_{\mathrm{C}}=+25^{\circ} \mathrm{C} \pm 2^{\circ} \mathrm{C}$.
6. The design, manufacturing process, and specifications of this device are subject to change without notice.
7. Derived mathematically from one or more of the following directly measured parameters: $\mathrm{f}_{\mathrm{C}}, \mathrm{IL}, 3 \mathrm{~dB}$ bandwidth, $\mathrm{f}_{\mathrm{C}}$ versus $\mathrm{T}_{\mathrm{C}}$, and $\mathrm{C}_{\mathrm{O}}$.
8. Turnover temperature, $\mathrm{T}_{\mathrm{O}}$, is the temperature of maximum (or turnover) frequency, $f_{O}$. The nominal frequency at any case temperature, $T_{C}$, may be calculated from: $f=f_{O}\left[1-F T C\left(T_{O}-T_{C}\right)^{2}\right]$. Typically oscillator $T_{O}$ is approximately equal to the specified resonator $\mathrm{T}_{\mathrm{O}}$.
9. This equivalent RLC model approximates resonator performance near the resonant frequency and is provided for reference only. The capacitance $C_{O}$ is the static (nonmotional) capacitance between the two terminals measured at low frequency ( 10 MHz ) with a capacitance meter. The measurement includes parasitic capacitance with "NC" pads unconnected. Case parasitic capacitance is approximately 0.05 pF . Transducer parallel capacitance can by calculated as: $\mathrm{C}_{\mathrm{P}} \approx \mathrm{C}_{\mathrm{O}}-0.05 \mathrm{pF}$.

## Electrical Connections

The SAW resonator is bidirectional and may be installed with either orientation. The two terminals are interchangeable and unnumbered. The callout NC indicates no internal connection. The NC pads assist with mechanical positioning and stability. External grounding of the NC pads is
 recommended to help reduce parasitic capacitance in the circuit.

## Typical Test Circuit

The test circuit inductor, $\mathrm{L}_{\text {TEST }}$, is tuned to resonate with the static capacitance, $\mathrm{C}_{\mathrm{O}}$, at $\mathrm{F}_{\mathrm{C}}$.


## POWER TEST



CW RF Power Dissipation $=P_{\text {INCIDENT }}-P_{\text {REFLECTED }}$

## Typical Application Circuits

## Typical Low-Power Transmitter Application



Typical Local Oscillator Applications


## Equivalent LC Model



## Temperature Characteristics

The curve shown on the right accounts for resonator contribution only and does not include LC component temperature contributions.

Typical Circuit Board


## Land Pattern

The circuit board land pattern
shown below is one possible design. The optimum land pattern is dependent on the circuit board assembly process which varies by manufacturer. The distance between adjacent land edges should be at a maximum to minimize parasitic capacitance. Trace lengths from terminal lands to other components should be short and wide to minimize parasitic series inductances.


## Case Design



| Dimensions | Millimeters |  |  | Inches |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | Min | Nom | Max | Min | Nom | Max |
| A | 4.87 | 5.0 | 5.13 | .191 | .196 | .201 |
| B | 3.37 | 3.5 | 3.63 | .132 | .137 | .142 |
| C | 1.45 | 1.53 | 1.60 | .057 | .060 | .062 |
| D | 1.35 | 1.43 | 1.50 | .040 | .057 | .059 |
| E | .67 | .80 | .93 | .026 | .031 | .036 |
| F | .37 | .50 | .63 | .014 | .019 | .024 |
| G | 1.07 | 1.20 | 1.33 | .042 | .047 | .052 |

